

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0877051021](#)  
**Status:** **Active**  
**Description:** 1.00mm (.039") Pitch DDR-II DIMM Socket, Vertical, Center Keys, 3.18mm (.125") Tail Length, Beige Latches, 0.38µm (15µ") Gold (Au) Plating, with Beveled Metal Pins, 240 Circuits, Lead-Free

**Documents:**

[3D Model](#) [Product Specification PS-87705-002 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

CSA 1409726  
 UL E29179

**General**

Product Family Memory Module Sockets  
 Series [87705](#)  
 Comments <LI>Latches in Beige Color  
 Component Type Socket  
 JEDEC Outline MO-237  
 Product Name DDR2 DIMM

**Physical**

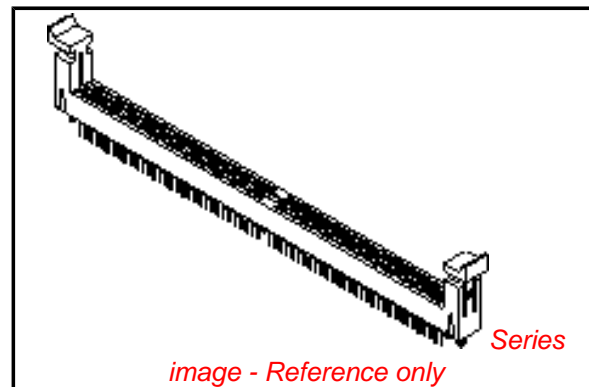
Circuits (Loaded) 240  
 Color - Resin Black, Natural  
 Durability (mating cycles max) 25  
 Entry Angle Vertical (Top Entry)  
 Flammability 94V-0  
 Keying to Mating Part Yes  
 Material - Metal Brass, Phosphor Bronze  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin  
 Material - Resin High Temperature Thermoplastic  
 PC Tail Length (in) 0.125 In  
 PC Tail Length (mm) 3.18 mm  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.093 In  
 PCB Thickness Recommended (mm) 2.40 mm  
 Packaging Type Tray  
 Pitch - Mating Interface (in) 0.039 In  
 Pitch - Mating Interface (mm) 1.00 mm  
 Plating min: Mating (µin) 15.2  
 Plating min: Mating (µm) 0.38  
 Plating min: Termination (µin) 101.6  
 Plating min: Termination (µm) 2.54  
 Temperature Range - Operating -10°C to +85°C  
 Termination Interface: Style Through Hole

**Electrical**

Current - Maximum per Contact 0.5A  
 Voltage - Maximum 30V  
 Voltage Key 1.8V, Center

**Solder Process Data**

Duration at Max. Process Temperature (seconds) 5  
 Lead-free Process Capability SMC & Wave Capable (TH only)  
 Max. Cycles at Max. Process Temperature 1



**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC Contains SVHC: No**  
**Halogen-Free Status**  
**Not Reviewed**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[87705Series](#)

**Mates With**

JEDEC standard 1.27mm modules

Process Temperature max. C 260

**Material Info**

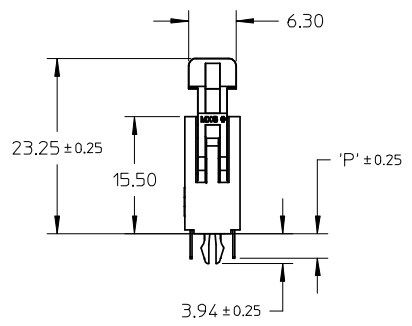
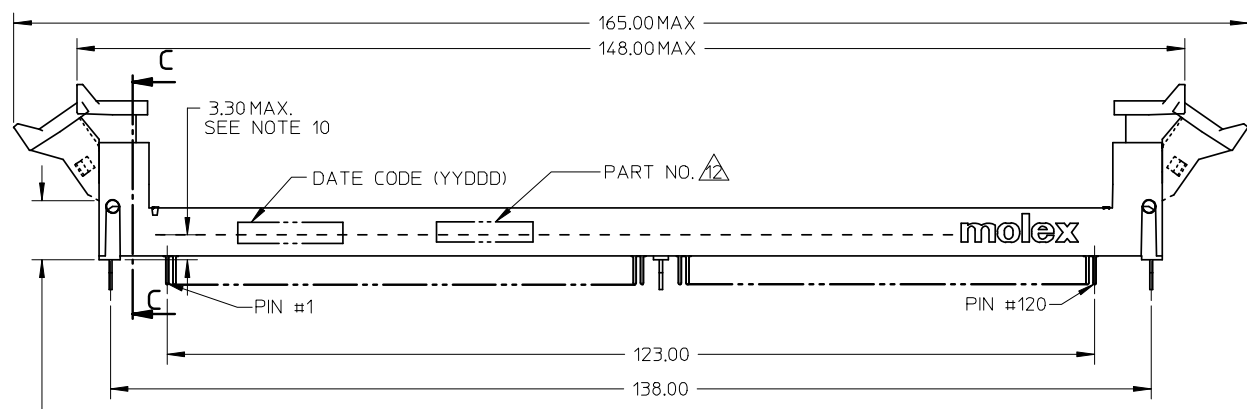
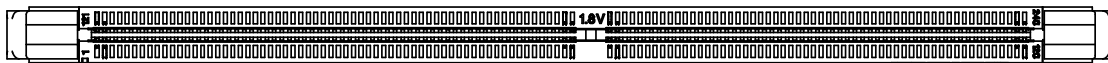
**Reference - Drawing Numbers**

Product Specification PS-87705-002  
Sales Drawing SD-87705-001

This document was generated on 05/27/2010

**PLEASE CHECK [WWW.MOLEX.COM](http://WWW.MOLEX.COM) FOR LATEST PART INFORMATION**

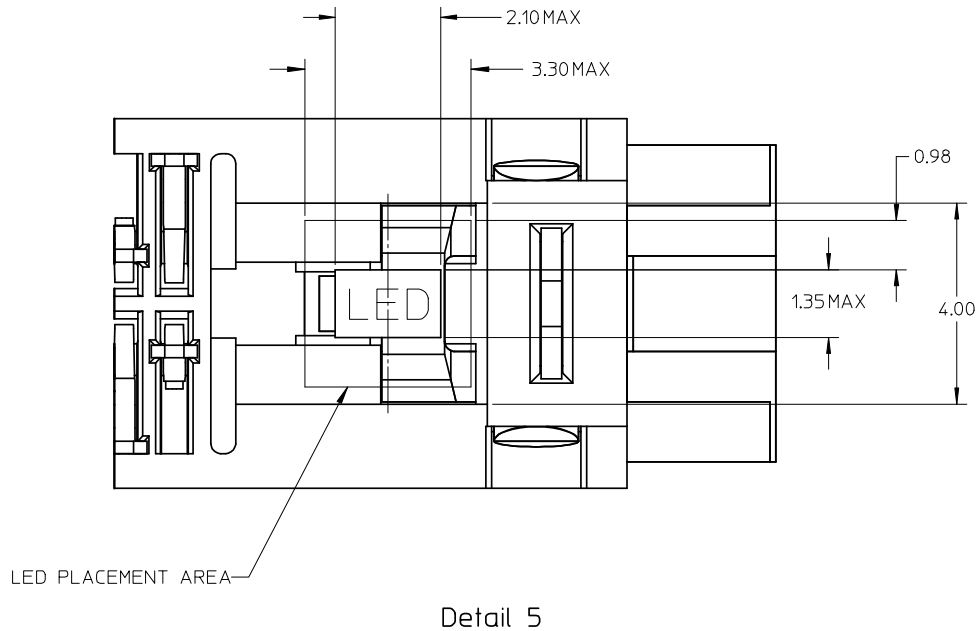
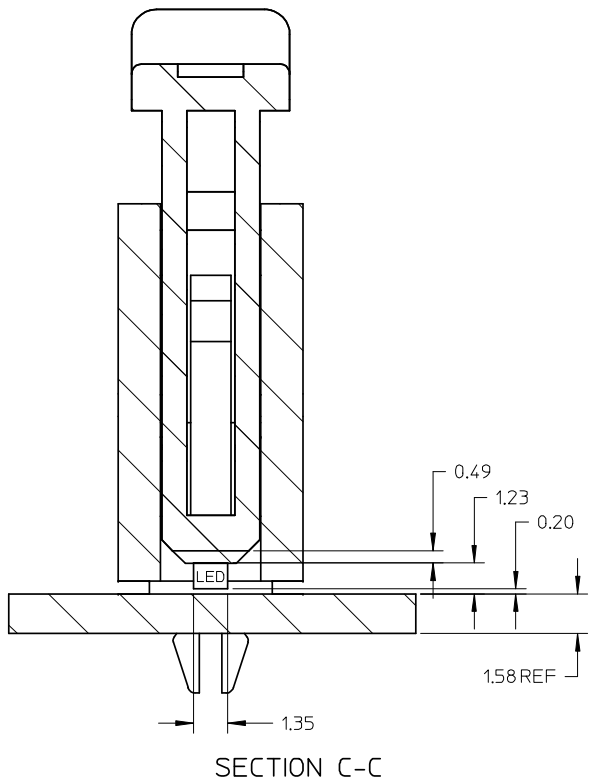
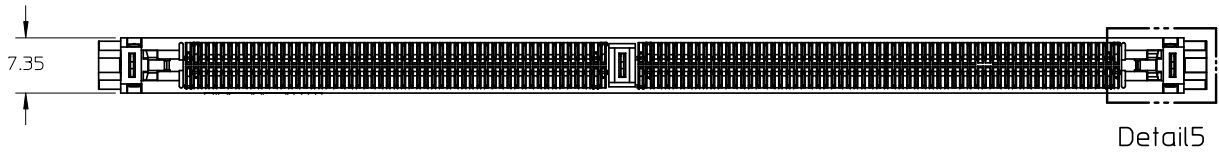
- NOTES:
- MATERIALS  
 HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0  
 COLOR: BLACK  
 EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0  
 COLOR: SEE TABLE  
 TERMINAL - COPPER ALLOY
  - PLATING - SEE TABLE IN SHEET 5 & 6.
  - CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.  
 (MEASURED OVER P.C. PADS)
  - RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.
  - REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE SPECIFICATIONS.
  - PRODUCT SHALL BE PACKED IN TRAY.
  - PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
  - KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.
  - REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.
  - DIMM MODULE SEATING PLANE FROM TOP OF PCB.
  - CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.
  - PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-\*\*\*\*



5.00 MIN  
LATCH KEEP  
OUT AREA

ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)			
		4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2002/07/22	MOLEX MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2002/07/23	DOCUMENT NO. SD-87705-001	SHEET NO. 1 OF 6		
			2 PLACES	± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			1 PLACE	± ---	± ---	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			ANGULAR ± 5 °		SEE TABLE					

10 9 8 7 6 5 4 3 2 1



ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRW:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		$\nabla=0$ $\square=0$	mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)			
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY DSOH	DATE 2002/07/22	MOLEX INCORPORATED			
			2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	APPROVED BY SKTOH	DATE 2002/07/23	DOCUMENT NO. SD-87705-001		SHEET NO. 2 OF 6	
		ANGULAR ± 5 °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3						

9 8 7 6 5 4 3 2 1









PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-0021	CENTER (1.8V)	2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	NATURAL
87705-1021		3.18	2.36		
87705-1053		3.66			
87705-0031		2.67	1.57	0.03µM / 1 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1031		3.18	2.36		
87705-0051		2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1051		3.18	2.36		

ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		=0 =0	mm      INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DRAWN BY CGOH      DATE 2002/05/09 CHECKED BY DS0H      DATE 2002/07/22 APPROVED BY SKTOH      DATE 2002/07/23	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		MATERIAL NO. SKTOH      DATE 2002/07/23		DOCUMENT NO. MOLEX INCORPORATED		SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87705-001		5 OF 6			
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-5051	CENTER (1.8V)	2.67	1.57	0.76μM / 30 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	CLEAR
87705-5151		3.18	2.36		
87705-6151		3.18	2.36	0.38μM / 15 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	
87705-9101		2.67	1.57	0.38μM / 15 μIN MIN. GOLD ON CONTACT, 2.54μM/ 100μIN MIN. TIN ON SOLDERTAILS, 1.27μM/ 50μIN MIN. NICKEL UNDERPLATE	

ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		 = 0  = 0	mm      INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: CGOH      DATE: 2002/05/09 CHECKED BY:      DATE: APPROVED BY:      DATE: 2002/07/23 SKTOH	TITLE	DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
		D1		SEE TABLE	 MOLEX INCORPORATED MATERIAL NO.      DOCUMENT NO. SD-87705-001 SHEET NO. 6 OF 6			



Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



## JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



Телефон: 8 (812) 309-75-97 (многоканальный)

Факс: 8 (812) 320-03-32

Электронная почта: [ocean@oceanchips.ru](mailto:ocean@oceanchips.ru)

Web: <http://oceanchips.ru/>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А